

TOSHIBA LED Lamp

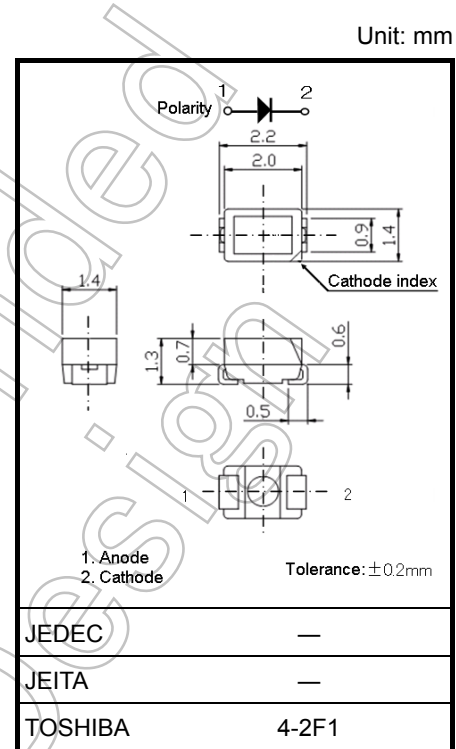
TLWD1060(T18)

Panel Circuit Indicator

- Surface-mount devices
- 2.2 (L) × 1.4 (W) × 1.3 (H) mm
- LED chip + phosphor
- Color: White C_x = 0.31 (typ), C_y = 0.30(typ), 90mcd(typ.) @10mA
- Low drive current, high-intensity light emission
- T_{opr} / T_{stg} = -40 to 100°C
- Applications: backlighting, pilot lamp etc.
- Standard embossed tape packing: T18 (3000 pcs / reel) 8-mm tape reel

Color and Material

Product Name	Color	Material
TLWD1060	White	InGaN



Weight: 0.01 g (typ.)

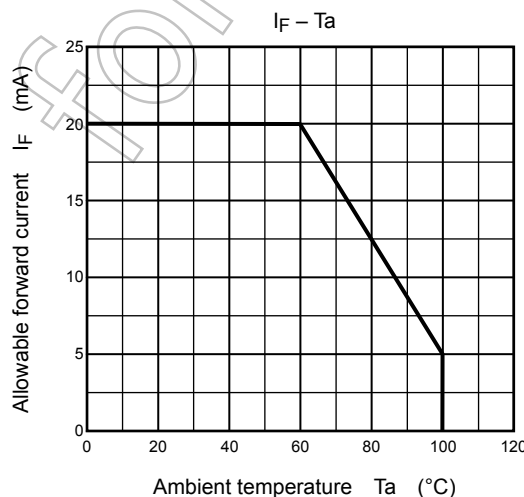
Absolute Maximum Ratings (Ta = 25°C)

Product Name	Forward Current I _F (mA) Please see Note 1	Reverse Voltage V _R (V)	Power Dissipation P _D (mW)	Operation Temperature T _{opr} (°C)	Storage Temperature T _{stg} (°C)
TLWD1060	20	4	76	-40 to 100	-40 to 100

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Forward current derating



Electrical Characteristics (Ta = 25°C)

Product Name	Forward Voltage V_F			Reverse Current I_R		
	Min	Typ.	Max	I_F	Max	V_R
TLWD1060	2.5	3.0	3.8	10	10	4
Unit	V			mA	μ A	V

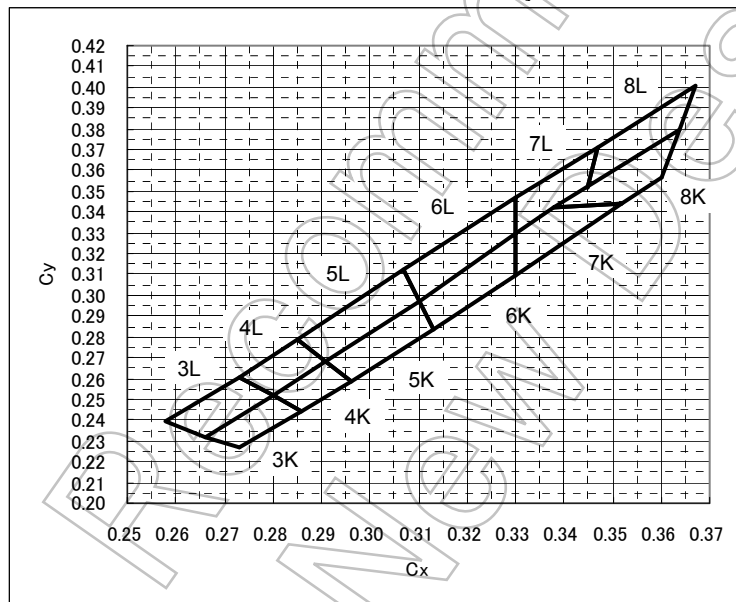
Optical Characteristics (Ta = 25°C)

Item	Symbol	Test condition	Min.	Typ.	Max.	Unit
Chromaticity coordinate	C_x	$I_F = 10$ mA	(Note 2)			—
	C_y	$I_F = 10$ mA	(Note 2)			—
Luminous intensity	I_V	$I_F = 10$ mA (Note 3)	40	90	200	mcd

Note 2: The product is tested at the following chromaticity coordinate groups.

Test conditions: $I_F=10$ mA, $T_a=25^\circ$ C

Accuracy: ± 0.01



(CIE1931)

	C_x	C_y		C_x	C_y		C_x	C_y
3K	0.273	0.227	5K	0.296	0.259	7K	0.330	0.310
	0.266	0.232		0.291	0.268		0.330	0.330
	0.280	0.252		0.310	0.297		0.338	0.342
	0.286	0.244		0.313	0.284		0.352	0.344
3L	0.266	0.232	5L	0.291	0.268	7L	0.330	0.330
	0.258	0.239		0.285	0.279		0.330	0.347
	0.273	0.261		0.307	0.312		0.347	0.371
	0.280	0.252		0.310	0.297		0.345	0.352
4K	0.286	0.244	6K	0.313	0.284	8K	0.352	0.344
	0.280	0.252		0.310	0.297		0.338	0.342
	0.291	0.268		0.330	0.330		0.364	0.380
	0.296	0.259		0.330	0.310		0.360	0.357
4L	0.280	0.252	6L	0.310	0.297	8L	0.345	0.352
	0.273	0.261		0.307	0.312		0.347	0.371
	0.285	0.279		0.330	0.347		0.367	0.401
	0.291	0.268		0.330	0.330		0.364	0.380

Note 3: Luminous Intensity classification

@Ta=25°C

Product name	Luminous Intensity I _v			I _F
	Min	Typ.	Max	
TLWD1060(T18)	40	—	200	10
	PA	40	80	
	QA	63	125	
	RA	100	200	
Unit	mcd			mA

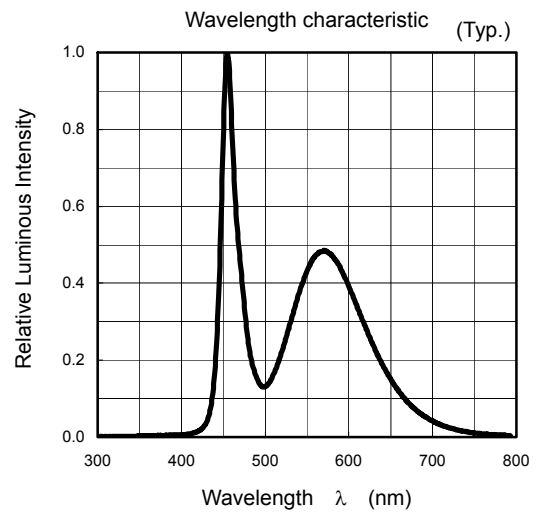
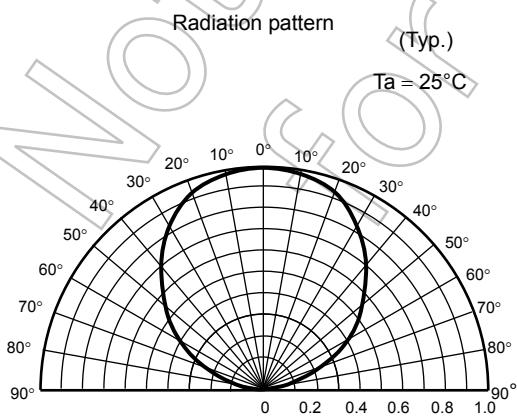
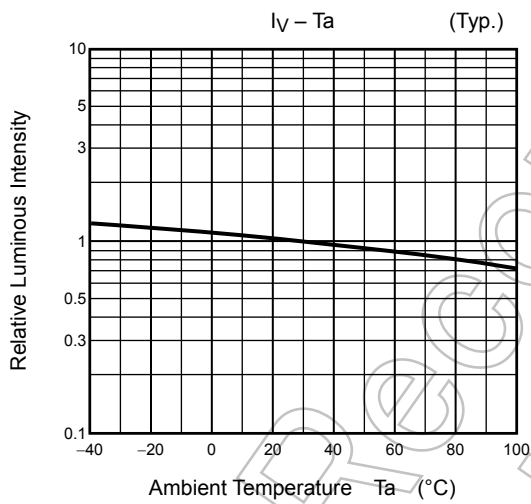
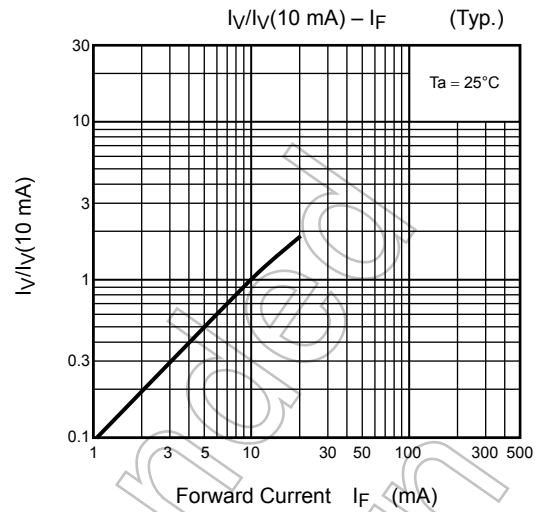
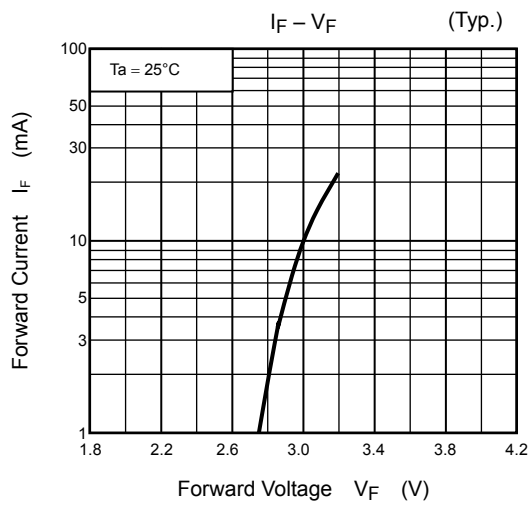
The specification on the above table is used for I_v classification of LEDs in Toshiba facility. Each reel includes the same rank LEDs. Let the delivery ratio of each rank be unquestioned.

The cautions

- ESD withstand voltage according to MIL STD 883D, Method 3015.7 : $\geq 1000V$
- When handling this LED, take the following measures to prevent the LED from being damaged or otherwise adversely affected.
 - 1) Use a conductive tablemat and conductive floor mat, and ground the workbench and floor.
 - 2) Operators handling laser diodes must be grounded via a high resistance (about 1M Ω). A conductive strap is good for this purpose.
 - 3) Ground all tools including soldering irons.
- This product is designed as a general display light source usage, and it has applied the measurement standard that matched with the sensitivity of human's eyes. Therefore, it is not intended for usage of functional application (ex. Light source for sensor, optical communication and etc) except general display light source.

Not Recommended for New Design

TLWD1060



Packaging

These LED devices are packed in an aluminum envelope with a silica gel and a moisture indicator to avoid moisture absorption. The optical characteristics of the devices may be affected by exposure to moisture in the air before soldering and they should therefore be stored under the following conditions:

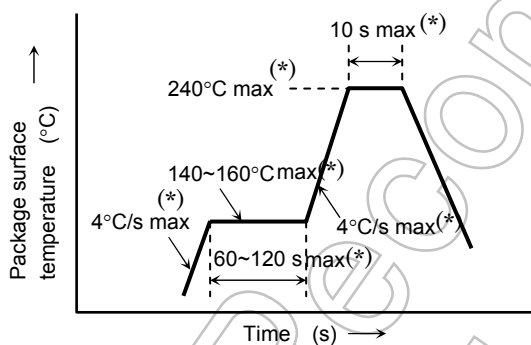
1. This moisture proof bag may be stored unopened within 12 months at the following conditions.
 Temperature: 5°C~30°C
 Humidity: 90% (max)
2. After opening the moisture proof bag, the devices should be assembled within 168 hours in an environment of 5°C to 30°C/60% RH or below.
3. If upon opening, the moisture indicator card shows humidity 30% or above (Color of indication changes to pink) or the expiration date has passed, the devices should be baked in taping with reel.
 After baking, use the baked devices within 72 hours, but perform baking only once.
 Baking conditions: 60±5°C, for 12 to 24 hours.
 Expiration date: 12 months from sealing date, which is imprinted on the label.
4. Repeated baking can cause the peeling strength of the taping to change, then leads to trouble in mounting. Furthermore, prevent the devices from being destructed against static electricity for baking of it.
5. If the packing material of laminate would be broken, the hermeticity would deteriorate. Therefore, do not throw or drop the packed devices.

Mounting Method

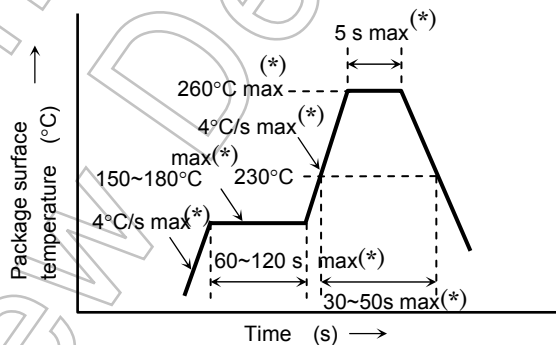
Soldering

- Reflow soldering

Temperature profile for Pb soldering (example)



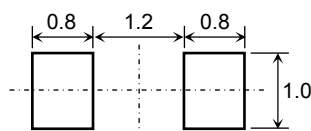
Temperature profile for Pb-free soldering (example)



- The products are evaluated using above reflow soldering conditions. No additional test is performed exceed the condition (i.e. the condition more than (*)MAX values) as a evaluation. Please perform reflow soldering under the above conditions.
- Please perform the first reflow soldering with reference to the above temperature profile and within 168 h of opening the package.
- Second reflow soldering
 In case of second reflow soldering should be performed within 168 h of the first reflow under the above conditions.
 Storage conditions before the second reflow soldering: 30°C, 60% RH (max)
- Make any necessary soldering corrections manually.
 (only once at each soldering point)
 Soldering iron: 25 W
 Temperature : 300°C or less
 Time : within 3 s
- Do not perform wave soldering.

Land pattern dimensions for reference only

Unit: mm



Cleaning

When cleaning is required after soldering, Toshiba recommends the following cleaning solvents. It is confirmed that these solvents have no effect on semiconductor devices in our dipping test (under the recommended conditions). In selecting the one for your actual usage, please perform sufficient review on washing condition, using condition and etc.

ASAHI CLEAN AK-225AES	: (made by ASAHI GLASS)
KAO CLEAN THROUGH 750H	: (made by KAO)
PINE ALPHA ST-100S	: (made by ARAKAWA CHEMICAL)

Precautions when Mounting

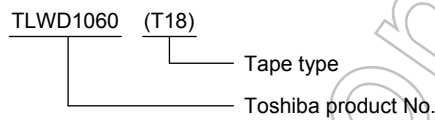
Do not apply force to the plastic part of the LED under high-temperature conditions. To avoid damaging the LED plastic, do not apply friction using a hard material. When installing the PCB in a product, ensure that the device does not come into contact with other components.

Tape Specifications

1. Product number format

The type of package used for shipment is denoted by a symbol suffix after the product number. The method of classification is as below. (this method, however does not apply to products whose electrical characteristics differ from standard Toshiba specifications)

- (1) Tape Type: T18 (4-mm pitch)
- (2) Example

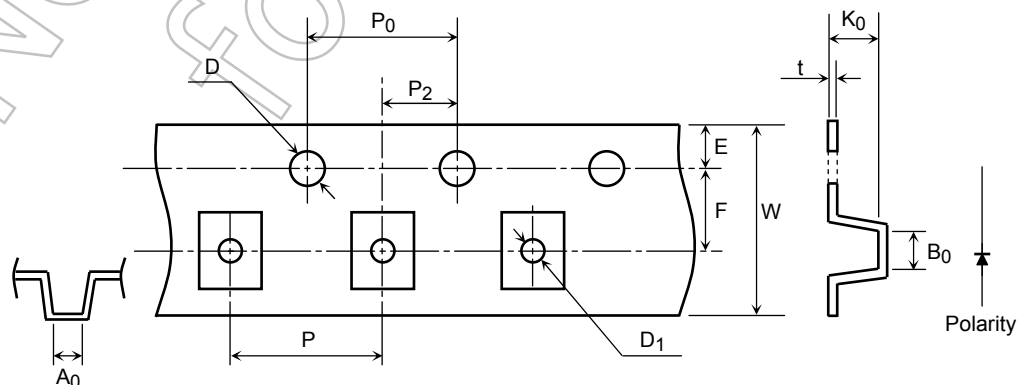


2. Tape dimensions

Unit: mm

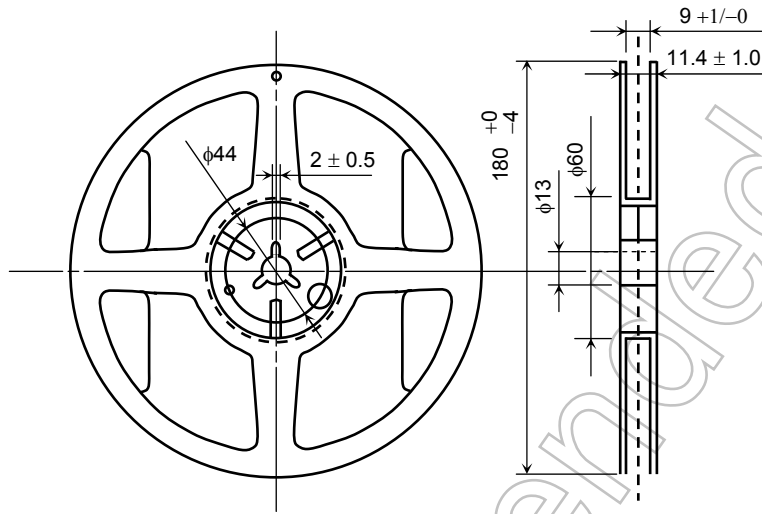
Symbol	Dimension	Tolerance
D	1.5	+0.1/-0
E	1.75	±0.1
P ₀	4.0	±0.1
t	0.2	±0.05
F	3.5	±0.05
D ₁	1.1	±0.1

Symbol	Dimension	Tolerance
P ₂	2.0	±0.05
W	8.0	±0.2
P	4.0	±0.1
A ₀	1.5	±0.1
B ₀	2.5	±0.1
K ₀	1.5	±0.1

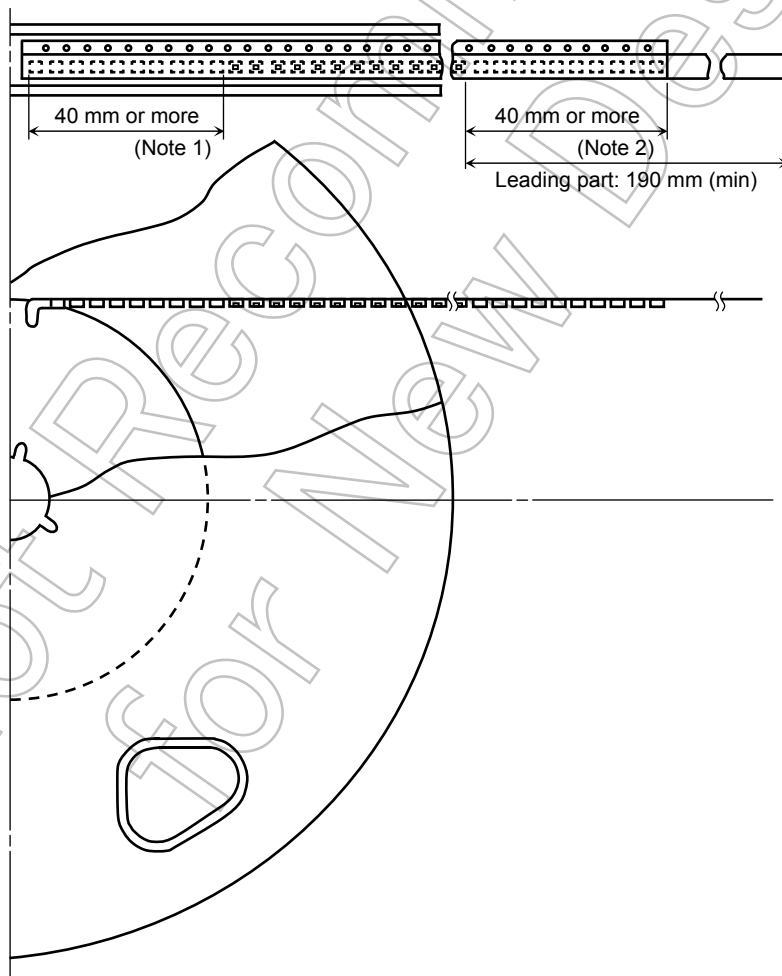


3. Reel dimensions

Unit: mm



4. Leader and trailer sections of tape



Note1: Empty trailer section

Note2: Empty leader section

5. Packing display

(1) Packing quantity

Reel	3,000 pcs
Carton	15,000 pcs

(2) Packing form: Each reel is sealed in an aluminum pack with silica gel.

6. Label format

(1) Example: TLWD1060 (T18)



P/N:

TYPE	TLWD1060		
ADDC	(T18)	Q'TY	3,000 pcs

Lot Number Key code for TSB 32C 3000
(RANK SYMBOL)

Use under 5-30degC/60%RH within 168h

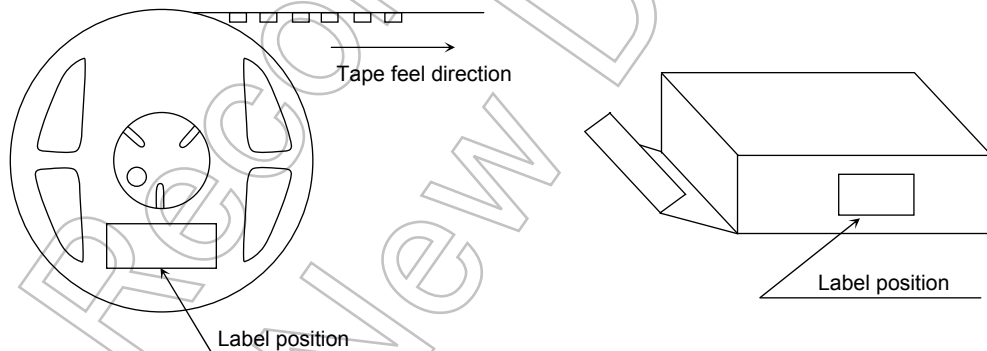
[[G]]/RoHS COMPATIBLE SEALED
Y380xxxxxxxxxxxxxxxxxxxx DIFFUSED IN *****
ASSEMBLED IN *****

(2) Label location

• Reel

• Carton



• The aluminum package in which the reel is supplied also has the label attached to center of one side.

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